

Title (en)
STUB MINIMIZATION FOR ASSEMBLIES WITHOUT WIREBONDS TO PACKAGE SUBSTRATE

Title (de)
SIMULATORMINIMIERUNG FÜR BAUGRUPPEN OHNE DRAHTBINDUNG AN VERPACKUNGSSUBSTRATE

Title (fr)
RÉDUCTION AU MINIMUM DES STUBS POUR MONTAGES SANS CONNEXION DES FILS AU SUBSTRAT DU BOÎTIER

Publication
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Application
EP 12778535 A 20120927

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Abstract (en)
[origin: WO2013052345A1] A microelectronic package (100) can include a substrate (102) and a microelectronic element (130) having a face (134) and one or more columns (138, 139) of contacts (132) exposed thereat which face and are joined to corresponding contacts exposed at a surface (120) of the substrate. An axial plane (140) may intersect the face along a line in a first direction (142) and centered relative to the columns of element contacts (132). Columns (104A, 104B) of package terminals can extend in the first direction. First terminals exposed at a central region (112) of the second surface can be configured to carry address information usable to determine an addressable memory location within the microelectronic element. The central region (112) may have a width (152) not more than three and one-half times a minimum pitch (150) between the columns of package terminals. The axial plane can intersect the central region.

IPC 8 full level
H01L 23/498 (2006.01); **H01L 25/065** (2006.01)

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